Parameter	Test/Measure	High Thermal Application		
		DN-1802C1	**DN-1806**	**DN-1906**
Curing Temp	degC	200	200	175
Viscosity @25deg.C	E-viscometer@5rpm	14,000	16,000	14,000
Thixotropic Index @25deg.C	0.5rpm/5rpm	7.0	3.85	3.5
Open Time (for 1*1 mm2 die size)	Hour	4	4	4
Volume Resistance	Ohm.cm	$9.0*10^{-5}$	$9.2*10^{-5}$	9.0*10-5
Thermal Conductivity	W/mk	85	70	80
Die Shear Strength @25 Deg.C with 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	30	28	30
	On Cu PCB (Mpa)	22	20	22
Die Shear Strength @260 Deg.C 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	10	10	10
	On Cu PCB (Mpa)	12	11	12
Storage Modulus@25 Deg.C	GPa	6.8	5.3	7
Tg	dC	72	78	74
CTE	ppm	25/79	25/79	36/169
Product Benefit		1.Good Workability 2.Solution for die size up to 15*15mm2	1.Good Workability 2.Solution for die size up to 15*15mm2	1. Good Workability 2. Solution for die size up to 15*15mm2